

SELECTED RECENT PUBLICATIONS

(as the Principal Author)

BOOKS:

Books:

Albert Wang, [*Practical ESD Protection Design*](#), IEEE-Wiley, New York, ISBN: 9781119850403, 2022 (available at [Amazon](#))

Albert Wang, *On-Chip ESD Protection for Integrated Circuits: an IC Design Perspective*, Kluwer/Springer, Boston, ISBN: 978-0792376477, 2002.

Book Edited:

J. Tang, Y. Li, H. Wu, B. Zhao and **Albert Wang**, *A Proceedings of IEEE Electron Devices Technology and Manufacturing (EDTM) Conference*, Edited, IEEE, ISBN: 978-1-7281-8176-9, 2021

SELECTED TOPICAL PUBLICATIONS

Journals: (My students in *Italic*)

- *C. Li, Z. Pan, X. Li, W. Hao, R. Miao and Albert Wang*, “Selective Overview of 3D Heterogeneity in CMOS”, *Nanomaterials* 2022, 12(14), 2340; July 2022.
- *Z. Pan, C. Li, W. Hao, X. Li and Albert Wang*, “ESD Protection Designs: Topical Overview and Perspective”, *IEEE Transactions on Device and Materials Reliability (TDMR)*, Vol. 22, No. 3, pp. 356-370, September 2022. DOI: [10.1109/TDMR.2022.3178420](https://doi.org/10.1109/TDMR.2022.3178420).
- *M. Di, Z. Pan, F. Zhang, C. Li, H. Wang and Albert Wang*, “A Study of ESD-mmWave-Switch Co-Design of 28GHz Distributed Travelling Wave Switch in 22nm FDSOI for 5G Systems”, *IEEE J. of Electron Devices Society (J-EDS)*, Vol. 6, pp. 1290-1296, December 2021. DOI: [10.1109/JEDS.2021.3131109](https://doi.org/10.1109/JEDS.2021.3131109).
- *M. Di, Z. Pan, F. Zhang, C. Li, H. Wang and Albert Wang*, “A Study of ESD-mmWave-Switch Co-Design of 28GHz Distributed Travelling Wave Switch in 22nm FDSOI for 5G Systems”, *IEEE J. of Electron Devices Society (J-EDS)*, Vol. 6, pp. 1290-1296, December 2021. DOI: [10.1109/JEDS.2021.3131109](https://doi.org/10.1109/JEDS.2021.3131109).
- *C. Li, M. Di, Z. Pan, F. Zhang, Q. Chen and Albert Wang*, “Investigating Graphene gNEMS ESD Switch for Design Optimization”, *IEEE J. of Electron Devices Society (J-EDS)*, Vol. 9, pp. 1172-1180, October 2021. DOI: [10.1109/JEDS.2021.3121995](https://doi.org/10.1109/JEDS.2021.3121995).
- *C. Li, F. Zhang, C. Wang, Z. Pan, M. Di and Albert Wang*, “Analyze Scalable Sudoku-Type DTSCR ESD Protection Array Structures in 22nm FDSOI”, *IEEE J. of Electron Devices Society (J-EDS)*, Vol. 9, pp. 1137-1144, September 2021. DOI: [10.1109/JEDS.2021.3110955](https://doi.org/10.1109/JEDS.2021.3110955).
- *M. Di, C. Li, Z. Pan and Albert Wang*, “Non-Pad-Based in Situ in-Operando CDM ESD Protection Using Internally Distributed Network”, *IEEE J. of Electron Devices*

Society (J-EDS), Vol. 9, pp. 1248-1256, December 2021. DOI: [10.1109/JEDS2021.3112736](https://doi.org/10.1109/JEDS2021.3112736).

- *C. Li, Q. Chen, J. Ng, M. Di, Z. Pan, T. Jones, Y-H. Xie, J. Hopkins, and Albert Wang*, “Emerging graphene-based on-chip ESD protection”, **Invited** review paper, *AAAFM Materials*, pp. 86-91, August 2021, [doi:10.24911/AAAFMMat/7-241](https://doi.org/10.24911/AAAFMMat/7-241).
- *M. Di, Z. Pan, C. Li and Albert Wang*, “ESD Design Verification Aided by Mixed-Mode Multiple-Stimuli ESD Simulation”, *IEEE J. of Electron Devices Society (J-EDS)*, Vol. 9, pp. 1194-1201, August 17, 2021, DOI:[10.1109/JEDS2021.3105375](https://doi.org/10.1109/JEDS2021.3105375)
- *C. Li, Q. Chen, J. Ng, F. Zhang, H. Wang, M. Di, Z. Pan, T. Wu, K. Zhang, X. Xie, Y. Xie and Albert Wang*, “Design, Fabrication and Characterization of Single-Crystalline Graphene gNEMS ESD Switches for Future ICs”, *IEEE Transactions on Device and Materials Reliability (TDMR)*, Vol. 21, No. 3, pp. 331-337, Sept. 2021, DOI: [10.1109/TDMR2021.3090311](https://doi.org/10.1109/TDMR2021.3090311).
- *J. Ng, T. Jones, I. Mattinez-Veils, Albert Wang, J. Hopkins and Y-H. Xie*, “Effects of polymer residue on the pull-in of suspended graphene”, *Journal of Vacuum Science & Technology B* 38, 023001 (2020); *J. Vac. Sci. Technol. B* Vol. 38, No. 2, 38(2) Mar/Apr 2020, pp. 023001-1 to 023001-10, DOI: 10.1116/1.5126439
- *Z. Pan, C. Li, M. Di, F. Zhang and Albert Wang*, “3D TCAD Analysis Enabling ESD Layout Design Optimization”, *IEEE J. of Electron Devices Society (J-EDS)*, Vol. 8, pp. 1289-1296, September 28, 2020. DOI: [10.1109/JEDS2020.3027034](https://doi.org/10.1109/JEDS2020.3027034)
- *C. Li, Q. Chen, F. Zhang, M. Di, Z. Pan, F. Lu and Albert Wang*, “Under-FET Thermal Sensor Enabling Smart Full-Chip Run-Time Thermal Management”, *IEEE J. of Electron Devices Society (J-EDS)*, Vol. 8, pp. 1242-1248, September, 2020. DOI: [10.1109/JEDS2020.3022730](https://doi.org/10.1109/JEDS2020.3022730)
- *M. Di, C. Li, Z. Pan and Albert Wang*, “Pad-Based CDM ESD Protection Methods Are Faulty”, *IEEE J. of Electron Devices Society (J-EDS)*, Vol. 8, pp. 1297-1304, September, 2020. DOI: [10.1109/JEDS2020.3022743](https://doi.org/10.1109/JEDS2020.3022743)
- *C. Wang, F. Zhang, F. Lu, Q. Chen, C. Li, and Albert Wang* “A Study of Transient Voltage Peaking in Diode-Based ESD Protection Structures in 28nm CMOS”, (Open Access Journal) *IEEE Access*, Vol. 8, pp. 87164 - 87172, May 6, 2020. DOI: [10.1109/ACCESS2020.2992496](https://doi.org/10.1109/ACCESS2020.2992496).
- *F. Zhang, C. Li, M. Di, Z. Pan, C. Li, N. Cahoon and Albert Wang*, “Design and Analysis of A 28GHz 9KV ESD-Protected Distributed Travelling-Wave TRx Switch in 22nm FDSOI”, *IEEE J. of Electron Devices Society (J-EDS)*, Vol. 8, pp. 655-661, Feb. 21, 2020. DOI: [10.1109/JEDS2020.2975598](https://doi.org/10.1109/JEDS2020.2975598)
- *C. Li, M. Di, Z. Pan and Albert Wang*, “Enabling 3D Heterogeneous Structures Towards Smart Chips: A Review”, *Advances in Science, Technology and Engineering Systems Journal (ASTESJ)*, Vol. 5, No. 1, pp. 267-273, February 2020. DOI: [10.25046/aj050134](https://doi.org/10.25046/aj050134)
- *Z. Pan, T. Lang, C. Li, M. Di, G. Chen, Y. Kalay, R. Pai, and Albert Wang*, “Visible Light Communication Cyber-Physical Systems-on-Chip for Smart Cities”, *J. of Communications*, Vol. 14, No. 12, pp. 1141-1146, December 2019. DOI:10.12720/jcm.14.12.1141-1146
- *C. Wang, Q. Chen, F. Lu, C. Li, F. Zhang and Albert Wang*, “Blocking Flying Crosstalk in BEOL Validated in Antenna Switches in 45nm SOI CMOS”, *IEEE*

Microwave and Wireless Components Letters (MWCL), Volume: 28, Issue: 11, pp. 1005-1007, November 2018. DOI: [10.1109/LMWC.2018.2873197](https://doi.org/10.1109/LMWC.2018.2873197)

- *F. Zhang, C. Wang, F. Lu, Q. Chen, C. Li, X. S. Wang, D. Li and Albert Wang, “A Full-Chip ESD Protection Circuit Simulation and Fast Dynamic Checking Method Using SPICE and ESD Behavior Models”, IEEE Trans. on Computer-Aided Design of Integrated Circuits and Systems, Vol. 38, No. 3, pp. 489-498, March 2019. DOI: [10.1109/TCAD.2018.2818707](https://doi.org/10.1109/TCAD.2018.2818707)*
- *J. Ng, Q. Chen, Y. Xie, Albert Wang and T. Wu, “Comparative Study Between the Fracture Stress of Poly- and Single- Crystalline Graphene Using a Novel NEMS Structure”, Micro & Nano Letters, Vol. 12, Issue 11, pp.907-912, November 2017. DOI: [10.1049/mnl.2017.0422](https://doi.org/10.1049/mnl.2017.0422)*
- *Q. Chen, J. Ng, C. Li, F. Lu, C. Wang, F. Zhang, Y-H. Xie and Albert Wang, “Systematic Transient Characterization of Graphene NEMS Switch for ESD Protection”, Micro & Nano Letters, Vol. 12, Issue 11, pp.875-880, November 2017. DOI: [10.1049/mnl.2017.0420](https://doi.org/10.1049/mnl.2017.0420)*
- *H. Tang, Y. Peng, X. Lu, Albert Wang and H. Wang, “A Quantitative Design Methodology for High-Speed Interpolation /Averaging ADCs,” Integration, the VLSI journal, Vol. 58, pp. 215-224, Jun. 2017. <https://doi.org/10.1016/j.vlsi.2017.03.008>,*
- *F. Lu, Q. Chen, C. Wang, F. Zhang, C. Li, R. Ma, X. S. Wang and Albert Wang, “In-Die Through-BEOL Metal Wall for Noise Isolation in 180nm FD-SOI CMOS”, IEEE Electron Device Letters, Vol. 38, No. 5, pp.630-632, May 2017. DOI: [10.1109/LED.2017.2682819](https://doi.org/10.1109/LED.2017.2682819);*
- *F. Lu, R. Ma, Z. Dong, L. Wang, C. Zhang, C. Wang, Q. Chen, X. S. Wang, F. Zhang, C. Li, H. Tang, Y. Cheng and Albert Wang, “A Systematic Study of ESD Protection Co-Design with High-Speed and High-Frequency ICs in 28nm CMOS”, IEEE Trans. Circuits and Systems I: Regular Papers, Vol. 63, Issue 10, pp.1746-1757, October, 2016. DOI: [10.1109/TCSI.2016.2581839](https://doi.org/10.1109/TCSI.2016.2581839)*
- *F. Lu, R. Ma, Z. Dong, L. Wang, C. Zhang, C. Wang, Q. Chen, X. S. Wang, F. Zhang, C. Li, H. Tang, Y. Cheng and Albert Wang, “A Systematic Study of ESD Protection Co-Design with High-Speed and High-Frequency ICs in 28nm CMOS”, IEEE Trans. Circuits and Systems I: Regular Papers, Vol. 63, Issue 10, pp.1746-1757, October, 2016. DOI: 10.1109/TCSI.2016.2581839*
- *Q. Chen, R. Ma, W. Zhang, F. Lu, C. Wang, O. Liang, F. Zhang, C. Li, H. Tang, Y-H Xie and Albert Wang, “Systematic Characterization of Graphene ESD Interconnects for on-Chip ESD Protection”, IEEE Trans. Electron Devices, Vol. 63, No. 8, pp. 3205-3212, July 2016. DOI: [10.1109/TED.2016.2582140](https://doi.org/10.1109/TED.2016.2582140)*
- *W. Zhang, R. Ma, Q. Chen, M. Xia, J. Ng, Albert Wang and Y-H Xie, “The electro-mechanical responses of suspended graphene ribbons for electrostatic discharge applications”, Applied Physics Letter, 108, 153103 (2016); doi: 10.1063/1.4946007 View online: <http://dx.doi.org/10.1063/1.4946007>, 2016.*
- *R. Ma, Q. Chen, W. Zhang, F. Lu, C. Wang, Albert Wang, Y. H. Xie and H. Tang , “A Dual-Polarity Graphene NEMS Switch ESD Protection Structure”, IEEE Electron Device Letters, V37, N5, pp. 674-676, April 2016. DOI: [10.1109/LED.2016.2544343](https://doi.org/10.1109/LED.2016.2544343)*
- *T. Lang, Z. Li, Albert Wang and G/ Chen, “Hemispherical Lens Featured Beehive Structure Receiver on Vehicular Massive MIMO Visible Light Communication System”, Internet of Vehicles - Safe and Intelligent Mobility, Vol. 9502, Print ISBN:*

978-3-319-27292-4, Online ISBN: 978-3-319-27293-1, Springer International Publishing, pp.469-477, November 2015. DOI: 10.1007/978-3-319-27293-1_41

- Z. Li, L. Liao, **Albert Wang** and G. Chen, "Vehicular Optical Ranging and Communication System", *EURASIP Journal on Wireless Communications and Networking* **2015/190**, July 2015 DOI: 10.1186/s13638-015-0415-1.
- X. S. Wang, X. Wang, F. Lu, C. Zhang, Z. Dong, L. Wang, R. Ma, Z. Shi, **Albert Wang**, M.-C. F. Chang, D. Wang, A. Joseph and C. P. Yue, "Concurrent Design Analysis of High-Linearity SP10T Switch with 8.5kV ESD Protection", *IEEE J. Solid-State Circuits*, V49, N9, pp. 1927–1941, September 2014. DOI: 10.1109/JSSC.2014.2331956
- H. Cai, Y. Yang, N. Qi, X. Chen, H. Tian, Z. Song, Y. Xu, C. Zhou, J. Zhan, **Albert Wang**, B. Chi and T.-L. Ren, "A 2.7-mW 1.36–1.86-GHz LC-VCO With a FOM of 202 dBc/Hz Enabled by a 26%-Size-Reduced Nano-Particle-Magnetic-Enhanced Inductor", *IEEE Trans. Microwave Theory and Techniques*, V6, N5, pp. 1211-1228, May 2014.
- C. Zhang, Z. Dong, F. Lu, R. Ma, L. Wang, H. Zhao, X. Wang, X. S. Wang, H. Tang and **Albert Wang**, "Fuse-Based Field-Dispensable ESD Protection for Ultra-High-Speed ICs", *IEEE Electron Device Letters*. V35, N3, pp.381-383, March 2014. DOI: [10.1109/LED.2014.2300496](https://doi.org/10.1109/LED.2014.2300496)
- J. Zhan, H. Cai, X. Chen, X. Wang, Q. Fang, Y. Yang, T. L. Ren, L. T. Liu, X. X. Li, **Albert Wang** and C. Yang, "Magnetic-Particle-Composite-Medium-Filled Stacked-Spiral Inductors for Radio-Frequency CMOS Applications", *Physics Letters*, 30(12), 2013.
- J. Zhan, C. Yang, X. Wang, T.-L. Ren, **Albert Wang**, Y. Yang and L.-T. Liu, "Integrated Stacked Spiral RF Inductor with Nanopowder Magnetic Core", *J. of Circuits, Systems, and Computers*, V22, N10, 2013, pp. 1340022-1 to 1340022-11, DOI: 10.1142/S0218126613400227.
- H.-L. Cai, J. Zhan, C. Yang, X. Chen, Y. Yang, B. Chi, **Albert Wang** and T.-L. Ren, "Application of ferrite nanomaterial in RF on-chip inductors," *Journal of Nanomaterials*, V2013, Article ID 832401, 2013. DOI: 10.1155/2013/832401.
- J. Zhan, C. Yang, X. Wang, Q. Fang, Z.T. Shi, Y. Yang, T.-L. Ren, **Albert Wang**, Y.H. Cheng and L.-T. Liu, "Stacked-spiral RF inductors with vertical nanoparticle magnetic core for radio-frequency integrated circuits in CMOS", *Elsevier Sensors & Actuators: A. Physical*, V195, pp. 231-238, June 2013, <http://dx.doi.org/10.1016/j.sna.2013.02.030>.
- Z. Ni, J. Zhan, Q. Fang, X. Wang, Z. Shi, Y. Yang, T.-L. Ren, **Albert Wang**, Y. Cheng, J. Gao, X. Li and C. Yang, "Design and Analysis of Vertical Nanoparticles- Magnetic-Cored Inductors for RF ICs", *IEEE Trans. Electron Devices*, V60, N4, pp. 1427-1435, April 2013. DOI: [10.1109/TED.2013.2245418](https://doi.org/10.1109/TED.2013.2245418)
- X. Wang, Z. Shi, J. Liu, L. Lin, H. Zhao, L. Wang, R. Ma, C. Zhang, Z. Dong, S. Fan, H. Tang, **Albert Wang**, Y. Cheng, B. Zhao, Z. Zhang, B. Chi and T. Ren, "Post-Si Programmable ESD Protection Circuit Design: Mechanisms and Analysis", *IEEE J. Solid-State Circuits*, V48, N5, pp. 1237-1249, May 2013. DOI: [10.1109/JSSC.2013.2255192](https://doi.org/10.1109/JSSC.2013.2255192)
- L. Wang, X. Wang, Z. Shi, R. Ma, J. Liu, Z. Dong, C. Zhang, L. Lin, H. Zhao, L. Zhang, **Albert Wang**, Y. Cheng and R. Huang, "Dual-Directional Nano Crossbar Array ESD

Protection Structures”, *IEEE Electron Device Letters*, V34, N1, pp. 111-113, January 2013. DOI: [10.1109/LED.2012.2222337](https://doi.org/10.1109/LED.2012.2222337).

- Z. Shi, X. Wang, J. Liu, L. Lin, H. Zhao, Q. Fang, L. Wang, C. Zhang, S. Fan, H. Tang, B. Li, **Albert Wang**, J. L. Liu, and Y. Cheng, “Programmable on-Chip ESD Protection Using Nano Crystal Dots Mechanism and Structures”, *IEEE Transactions on Nanotechnology*, V11, N5, pp.884-889, September 2012. DOI: 10.1109/TNANO.2012.2204767.
- X. Wang, H. Tang, L. Lin, J. Liu, Q. Fang, H. Zhao, **Albert Wang**, Z. Shi, S. Fan, B. Zhao, L. W. Yang, J. He and Y. Cheng, “Co-design of ESD protection and UWB RF front-end ICs”, *Science China*, Vol. 54 No. 10, pp.2209–2220, Oct. 2011. DOI: 10.1007/s11432-011-4416-3.
- J. Zhan, C. Yang, X. Wang, F. Zhang, T.L. Ren, **Albert Wang**, Y. Yang, L. T. Liu, L. W. Yang and Z. X. Yue, "Stacked-Spiral RF Inductor with Vertical Nano-Powder-Magnetic-Core in CMOS", *IEEE Microwave and Wireless Components Letters (MWCL)*, Vol. 22, No. 1, pp29-31, January 2011.
- S. Fan, H. Tang, H. Zhao, **Albert Wang** and B. Zhao, “Enhanced Offset Averaging Technique for Flash ADC Design”, *Tsinghua Science and Technology*, ISSN1007-0214ll02/17, Vol. 16, No. 3, pp.285-289, June 2011.
- J. Liu, X. Wang, H. Zhao, Q. Fang, **Albert Wang**, L. Lin, H. Tang, S. Fan, B. Zhao, S. Wen and R. Wong, “Design and Analysis of Low-Voltage Low-Parasitic ESD Protection for RF ICs in CMOS”, *IEEE Journal of Solid-State Circuits*, V46, N5, pp.1100-1110, May 2011. DOI: 10.1109/JSSC.2011.2118290.
- X. Wang, S. Fan, H. Tang, L. Lin, J. Liu, Q. Fang, H. Zhao, **Albert Wang**, L. Yang and B. Zhao, “A Whole-Chip ESD-Protected 0.14pJ/p-mV 3.1-10.6GHz Impulse-Radio UWB Transmitter in 0.18μm CMOS”, *IEEE Transactions on Microwave Theory and Techniques*, V59, N4, pp.1109-1116, April 2011.
- L. Lin, L. Zhang, X. Wang, J. Liu, H. Zhao, H. Tang, Q. Fang, Z. Shi, **Albert Wang**, R. Huang, and Y. Cheng, “Novel Nanophase-Switching ESD Protection”, *IEEE Electron Device Letters (EDL)*, V32, N3, pp.378-380, March 2011.
- H. Tang, H. Zhao, S. Fan, X. Wang, L. Lin, Q. Fang, J. Liu and **Albert Wang**, “Design Matrix Analysis for Capacitive Interpolation Flash ADC”, *ASP Journal of Low Power Electronics*, Vol. 7, No. 1, pp. 61-70, Feb. 2011. DOI: <http://dx.doi.org/10.1166/jolpe.2011.1117>
- X. Wang, X. Guan, S. Fan, H. Tang, H. Zhao, L. Lin, Q. Fang, J. Liu, **Albert Wang** and L. Yang, “ESD-Protected Power Amplifier Design in CMOS for Highly Reliable RF ICs”, *IEEE Transactions on Industrial Electronics*, V58, N7, pp2736-2743, July 2011. DOI: 10.1109/TIE.2010.2057234.
- X. Wang, L. Lin, H. Tang, H. Zhao, Q. Fang, J. Liu, S. Fan, **Albert Wang**, B. Zhao, L. Yang and G. Zhang, “Low Power 3.1-10.6GHz IR-UWB Transmitter for Gbps Wireless Communications”, *Science China*, Vol. 54 No. 5, pp.1094–1102, May 2011. DOI: 10.1007/s11432-011-4222-y.
- G. Chen, X. Wang, S. Fan, H. Tang, L. Lin and **Albert Wang**, “ESD-Induced Noise to Low Noise Amplifier Circuits in BiCMOS”, *Tsinghua Science and Technology*, ISSN1007-0214ll02/17, Vol. 15, No. 3, pp259-264, June 2010.
- X. Wang, J. Liu, S. Fan, L. Lin, H. Tang, **Albert Wang**, H. Chen, L. Yang and B. Zhao, “Cross-Coupling Low-Triggering Dual-Polarity CLTdSCR ESD Protection in

CMOS”, *IEEE Electron Device Letters (EDL)*, Vol. 31, No. 10, pp.1143-1145, October 2010.

- *X. Wang, S. Fan, H. Zhao, L. Lin, Q. Fang, H. Tang and Albert Wang*, “Whole-Chip ESD Protection Design for RF and AMS ICs”, *Tsinghua Science and Technology*, ISSN1007-0214ll03/17, Vol. 15, No. 3, pp265-274, June 2010.
- *C. Yang, F. Liu, X. Wang, J. Zhan, Albert Wang, T. Ren, L. Liu, H. Long, Z. Wu, X. Li*, “Investigation of on-Chip Soft-Ferrite-Integrated Inductors for RF ICs — Part I: Design and Simulation”, in press, *IEEE Trans. Electron Devices*, 2009.
- *C. Yang, F. Liu, X. Wang, J. Zhan, Albert Wang, T. Ren, L. Liu, H. Long, Z. Wu, X. Li*, “Investigation of on-Chip Soft-Ferrite-Integrated Inductors for RF ICs — Part II: Experiments”, in press, *IEEE Trans. Electron Devices*, 2009.
- *H. Xie, X. Wang, L. Lin, H. Tang, Q. Fang, H. Zhao, S. Wang, F. Yao, Albert Wang and Y. Zhou*, “A 52mW 3.1-10.6GHz Fully Integrated Correlator for IR-UWB Transceivers in 0.18μm CMOS”, in press, *IEEE Trans. Industrial Electronics*, 2009.
- *L. Zhang, R. Huang, D. Gao, D. Wu, Y. Kuang, P. Tang, W. Ding, Albert Wang and Y. Wang*, “Unipolar Resistive Switch Based on Silicon Monoxide Realized by CMOS Technology”, *IEEE Electron Device Letters*, Vol. 30, No. 8, August 2009, pp.870-872.
- *X. Guan, X. Wang, Albert Wang and B. Zhao*, “A 3V 110μW 3.1ppm/C curvature-compensated CMOS bandgap reference”, in press, *Analog Integrated Circuits and Signal Processing, An International Journal*, DOI#: 0.1007/s10470-009-9333-7, 2009.
- *Bo Qin, Hongyi Chen, Xin Wang and Albert Wang*, “An Ultra Low-Power FCC-Compliant 5th-Derivative Gaussian Pulse Generator for IR-UWB Transceiver”, *Journal of Electronics*, Vol. 18, No. 4, pp. 605-609, Oct. 2009.
- *B. Qin, X. Wang, H. Xie, L. Lin, H. Tang, Albert Wang, H. Chen, B. Zhao, L. Yang and Y. Zhou*, “1.8pJ/pulse Programmable Gaussian Pulse Generator for Full-Band Non-Carrier Impulse UWB Transceivers in 90nm CMOS”, in press, *IEEE Trans. Industrial Electronics*, 2009.
- **Albert Wang, L. Lin, X. Wang and H. Liu**, “Emerging Challenges in ESD Protection for RF ICs in CMOS”, **Invited**, *J. of Semiconductors*, 29(4), pp628-636, April 2008.
- *C. Yang, F. Liu, T. Ren, L. Liu, G. Chen, X. Guan, Albert Wang and H. Feng*, “Ferrite-Integrated on-Chip Inductors for RF ICs”, *IEEE Electron Device Letters*, Vol. 28, No. 7, pp652-655, July 2007.
- *F. Liu, C. Yang, T. Ren, Albert Wang, J. Yu and L. Liu*, “NiCuZn ferrite thin films grown by a sol-gel method and rapid thermal annealing,” *Journal of Magnetism and Magnetic Materials*, Volume 309, Issue 1, pp75-79, February 2007.
- *F. Liu, C. Yang, T. Ren, Albert Wang, J. Yu and L. Liu*, “NiCuZn Ferrite Thin Films Grown by a sol-gel Method and Rapid Thermal Annealing,” *J. of Magnetism and Magnetic Materials*, V309, Issue 1, pp.17-21, March 2007.
- *C. Yang, F. Liu, T. Ren, L. Liu, H. Feng, Albert Wang and H. Long*, “Fully Integrated Ferrite-Based Inductors for RF ICs”, *Sensors & Actuators: A. Physical*, A 130-131, p365-370, 2006.
- *F. Liu, T. Ren, C. Yang, L. Liu, Albert Wang, and J. Yu*, “NiCuZn Ferrite Thin Films for RF Integrated Inductors,” *Materials Letter*, vol. 60, pp. 1403-1406, 2006.
- *T. Ren, C. Yang, F. Liu, L. Liu, Albert Z. Wang and X. Zhang*, “Equivalent Circuit Analysis of an RF Integrated Inductor with Ferrite Thin-Film,” *Journal of Semiconductors*, vol. 27, pp. 511-515, 2006.

- *C. Yang, F. Liu, T. Ren, L. Liu, H. Feng, Albert Z. Wang, H. Long and J. Yu*, “RF Integrated Inductor with CoZrO Ferrite Thin Film,” *Journal of Semiconductors*, vol. 26, pp. 2208-2212, 2005.
- **Albert Wang, H. Feng, R. Zhan, H. Xie, G. Chen, Q. Wu, X. Guan, Z. Wang and C. Zhang**, “A Review on RF ESD Protection Design”, *IEEE Trans. Electron Devices*, Vol. 52, No. 7, pp. 1304-1311, July 2005.
- *H. Long, Z. Feng, H. Feng, Albert Wang, T., Ren, J. Bao, F. Liu, C. Yang, X. Zhang*, “A New Modeling Technique for Simulating 3D Arbitrary Conductor-Magnet Structures for RFIC Applications”, *IEEE Tans. Electron Devices*, Vol. 52, No. 7, pp. 1354-1363, July 2005.
- *H. Xie, H. Feng, R. Zhan, Albert Wang, D. Rodriguez and D. Rice*, “A New Low-Parasitic Polysilicon SCR ESD Protection Structure for RF ICs”, *IEEE Electron Device Letters*, Vol. 26, No.2, pp.121-123, February 2005.
- *R. Zhan, H. Feng, Q. Wu, H. Xie, X. Guan, G. Chen and Albert Z. Wang*, “ESDInspector: A New Layout-level ESD Protection Circuitry Design Verification Tool Using a Smart-Parametric Checking Mechanism”, *IEEE Trans. CAD of Integrated Circuits and Systems*, Vol. 23, No. 10, pp.1421-1428, October 2004.
- *G. Chen, H. Feng, H. Xie, R. Zhan, Q. Wu, X. Guan, Albert Wang, K. Takasuka, S. Tamura, Z. Wang and C. Zhang*, “Characterizing Diodes for RF ESD Protection”, *IEEE Electron Device Letters*, Vol. 25, No. 5, pp.323-325, May 2004.
- *H. Feng, R. Zhan, G. Chen, Q. Wu and Albert Z. Wang*, “Electrostatic Discharge Protection for RF Integrated Circuits: New ESD Design Challenges”, *Analog Integrated Circuits and Signal Processing, An International Journal*, Vol. 39, Issue 1, pp. 5-19, April 2004.
- *R. Zhan, H. Feng, Q. Wu and Albert Wang*, “ESDExtractor: A New Technology-Independent CAD Tool for Arbitrary ESD Protection Device Extraction,” *IEEE Trans. CAD of Integrated Circuits and Systems*, Vol. 22, No. 10, pp.1362-1370, October 2003.
- *H. Long, Z. Feng, H. Feng and Albert Wang*, “A Novel Accurate PEEC-based 3D Modeling Technique for RF Devices of Arbitrary Conductor-Magnet Structure,” *Microwave and Optical Technology Letters*, V38, Issue 3, Wiley & Sons, pp.237-240, August 2003.
- *H. Feng, G. Chen, R. Zhan, Q. Wu, X. Guan, H. Xie, Albert Wang and R. Gafiteanu*, “A Mixed-Mode ESD Protection Circuit Simulation-Design Methodology,” *IEEE J. Solid-State Circuits*, V38, N6, pp.995-1006, June 2003.
- *H. Feng, R. Zhan, Q. Wu, G. Chen and Albert Wang*, “RC-SCR: A Very-Low-Voltage ESD Protection Circuit in Plain CMOS,” *IEE Electronics Letters*, V38, N19, pp.1099-1100, September 2002.
- *H. G. Feng, R. Y. Zhan, Q. Wu, G. Chen and Albert Z. Wang*, “A Circular Under-Pad Multiple-Mode ESD Protection Structure for ICs,” *IEE Electronics Letters*, V38, N11, pp. 511 –513, May 2002.
- *H. G. Feng, K. Gong, R. Zhan and Albert Wang*, “A Novel all-Direction on-Chip Protection Circuit,” *IEICE Trans. Electron.*, Vol. E85-C, N3, pp.566-571, March 2002.
- *K. Gong, H. Feng, R. Zhan and Albert Z. Wang*, “A Study of Parasitic Effects of ESD Protection on RF ICs,” *IEEE Trans. Microwave Theory and Techniques*, V50, N1, pp.393-402, January 2002.

- *H. Feng, R. Zhan, K. Gong and Albert Z. Wang*, “A New Pad-Oriented Multiple-Mode ESD Protection Structure and Layout Optimization,” *IEEE Electron Device Letters*, V22, N10, pp.493-495, Oct. 2001.
- *K. Gong, H. G. Feng, R. Y. Zhan and Albert Z. Wang*, “ESD-Induced Circuit Performance Degradation in RFICs,” *Microelectronics Reliability*, V41, Issue 9-10, Elsevier Science, pp.1379-1383, September-October 2001.
- **Albert Z. Wang, H. G. Feng, K. Gong, R. Y. Zhan and J. Stine**, “On-Chip ESD Protection Design for Integrated Circuits: An Overview for IC Designers,” *Microelectronics Journal*, Elsevier Science, V32, Issue 9, pp.733-747, September 2001.
- *H. G. Feng, K. Gong, R. Zhan and Albert Wang*, “A Pad-Oriented Novel Electrostatic Discharge Protection Structure for Mixed-Signal ICs,” in *Advances in Systems Science: Measurement, Circuits and Control*, Edited by N. Mastorakis and L. Pecorelli-Peres, Electrical and Computer Engineering Series, WSES Press, pp.159-163, 2001.
- *H. G. Feng, K. Gong and Albert Z. Wang*, “A Novel on-Chip Electrostatic Discharge Protection Design for RFIC’s,” *Microelectronics Journal*, V32, Issue 3, Elsevier Science, pp 189-195, March 2001.
- **Albert Wang** and C. Tsay, “On a Dual-Direction on-Chip Electrostatic Discharge Protection Structure,” *IEEE Trans. Electron Devices*, V48, N5, pp.978-984, May 2001.
- **Albert Wang** and C. Tsay, “An on-Chip ESD Protection Circuit with Low Trigger-Voltage in BiCMOS Technology,” *IEEE J. Solid-State Circuits*, V36, N1, pp.40-45, January 2001.
- **Albert Wang**, C. Tsay, and P. Deane, “A Study of NMOS Behaviors under ESD Stress: Simulation and Characterization,” *Microelectronics Reliability*, V38, Issue 6-8, Elsevier Science, pp.1183-1186, 1998.
- **Albert Wang** and W. Anderson, “Fabrication and Characterization of a Depletion-mode $Zn_{0.07}Sse_{0.93}$ MESFET,” *IEEE Electron Device Lett.*, Vol.17, N5, pp.217-219, May1996.
- **Albert Wang** and W. Anderson, “Metal-Semiconductor Contacts to n- $Zn_{0.07}Sse_{0.93}$,” *J. Electronic Materials*, V25, N2, pp.201-206, February 1996.
- **Albert Z. Wang** and W. A. Anderson, “Enhancement of the Schottky Barrier Height of Au/ZnSSe Diodes,” *Applied Physics Letters*, V66, N15, pp.1963-1965, April 1995.
- **Albert Z. Wang**, W. A. Anderson and M. A. Haase, “Electrical Properties of Schottky Contacts to N-type $Zn_{0.07}Sse_{0.93}$ Epilayers,” *J. Applied Physics*, V77, N7, pp.3513-3517, April 1995.
- **Albert Z. Wang** and W. A. Anderson, “Influence of a Single InGaAs Quantum Well on Current Transport and Deep Levels in GaAs,” *Solid State Electronics*, V38, N3, pp.673-678, March 1995.
- **Z. H. (Albert) Wang** and X. L. Chen, “On Asymmetric LDD MOSFETs,” *J. Semiconductors*, V11, N2, pp.136-141, February 1990.

Conference Proceedings: (My students in *Italic*)

- *M. Di, W. Hao, X. Li, Z. Pan, R. Miao and Albert Wang*, “A 38GHz SPDT Traveling Wave Switch with 5A CDM ESD Protection in 45nm PDSOI for 5G System”, Accepted, *Proc. IEEE Radio and Wireless Symposium (RWS), Radio & Wireless Week (RW)*, 2023.

- *W. Hao, M. Di, Z. Pan, X. Li, R. Miao, N. Cahoon and Albert Wang*, “A 60GHz Traveling-Wave SPDT Switch with HBM and CDM ESD Protection in 45nm SOI CMOS”, **Invited**, *Proc. IEEE International Conference on Solid-State and Integrated Circuit Technology (ICSICT)*, 2022.
- *Z. Pan, W. Hao, X. Li, R. Miao, C. Li and Albert Wang*, “Think Nontraditionally for Future ESD Protection”, **Invited**, *Proc. EOS/ESD Symp*, 2022.
- *Z. Pan, W. Hao, X. Li, R. Miao and Albert Wang*, “Design for EMI/ESD Immunity”, **Invited**, *Proc. International Flexible Electronics Technology Conference (IFETC)*, 2022.
- **Albert Wang**, “Nanotechnologies enabling future on-chip ESD protection”, **Invited**, Abstract in *IEEE Microelectronics Design and Test Symposium (MDTS)*, 2022. (no proceedings)
- **Albert Wang**, “Cross-Layer ESD Protection Designs: Chips, Packaging and Systems”, **Invited**, *IEEE Symposium on Reliability for Electronics and Photonics Packaging (REPP)*, 2021.
- *C. Li, Q. Chen, J. Ng, M. Di, Z. Pan, T. Jones, Y-H. Xie, J. Hopkins and Albert Wang*, “Using graphene-based devices and interconnects for IC Reliability”, **Invited**, *International Conference on Advances in Functional Materials in UCLA (AAAFM-UCLA)*, 2021.
- *F. Zhang, C. Li, M. Di, Z. Pan, H. Wang and Albert Wang*, “ESD Co-Design of mm-Wave RF Switch in 22nm SOI”, *Proc. IEEE Electron Devices Technology and Manufacturing Conference (EDTM)*, pp. 1-3, 2021. (**Best Paper Award, Finalist**)
- *M. Di, Z. Pan, C. Li and Albert Wang*, “Internal-Distributed CDM ESD Protection”, *Proc. IEEE Electron Devices Technology and Manufacturing Conference (EDTM)*, pp. 313-315, 2021.
- *C. Li, M. Di, Z. Pan and Albert Wang*, “A Study of Materials Impacts on Graphene Electrostatic Discharge Switches”, *Proc. IEEE Electron Devices Technology and Manufacturing Conference (EDTM)*, pp. 694-696, 2021. (**Best Student Paper Award, Finalist**)
- *C. Li, F. Zhang, Z. Pan, M. Di, C. Wang and Albert Wang*, “Sudoku DTSCR ESD Array in 22nm FDSOI”, *Proc. IEEE Electron Devices Technology and Manufacturing Conference (EDTM)*, pp. 118-120, 2021.
- *M. Di, Z. Pan, C. Li and Albert Wang*, “A New Multi-Stimuli-Based Simulation Method for ESD Design Verification”, *Proc. IEEE Electron Devices Technology and Manufacturing Conference (EDTM)*, pp. 4-6, 2021.
- *C. Li, M. Di, Z. Pan, H. Wu and Albert Wang*, “Vertical TSV-Like Diode ESD Protection”, *Proc. IEEE Electron Devices Technology and Manufacturing Conference (EDTM)*, pp. 676-678, 2021.
- *L. Shen, Y. Lv, L. Jiang, Z. Kong, Y. Lu, Q. Chen, Albert Wang and Y. Cheng*, “A Study of the Electrical and Mechanical Reliability Properties of Suspended Graphene NEMS Devices for ESD Protection Applications”, *Proc. IEEE Electron Devices Technology and Manufacturing Conference (EDTM)*, pp. 637-639, 2021.
- *T. Lang, Z. Pan, N. Ortiz, G. Chen, Y. Kalay, R. Pai and Albert Wang*, “Integrated Design of Low Complexity RSS Based Visible Light Indoor Positioning and Power Line Communication System for Smart Hospitals”, *Proc. IEEE International Conference on Consumer Electronics (ICCE)*, 2021.

- Y. E. Kalay, H. Sathyaranarayanan, D. Schaumann, **Albert Wang**, G. Chen and R. G. Pai, “Simulation-powered smart buildings management enabled by visible light communication”, *Proc. Symposium on Simulation in Architecture + Urban Design (SimAUD)*, pp. 531-538, 2020.
- C. Li, Q. Chen, F. Zhang, M. Di and **Albert Wang**, “Built-in-Hole a-IGZO p-i-n Diode for Chip-Scale Temperature Mapping”, *Proc. International Conference on Advances in Functional Materials in UCLA (AAAFM-UCLA)*, 2020.
- Y. Kalay, H. Sathyaranarayanan, D. Schaumann, **Albert Wang**, G. Chen and R. G. Pai, “VLC-Enabled Human-Aware Building Management System”, *Proc. 22nd International Conference on Human-Computer Interaction (HCII2020)*, pp. 207-222, 2020.
- C. Li, Z. Pan, M. Di, F. Zhang, Z. Li, N. Jiang and **Albert Wang**, “ESD Device Layout Design Guidelines by 3D TCAD Simulation”, *Proc. IEEE Electron Devices Technology and Manufacturing Conference (EDTM)*, pp. 672-675, 2020.
- C. Li, Q. Chen, M. Di, F. Zhang and **Albert Wang**, “In-Hole Diodes for on-Chip Thermal Sensing”, *Proc. IEEE Electron Devices Technology and Manufacturing Conference (EDTM)*, pp.683-686, 2020.
- M. Di, C. Li, Z. Pan and **Albert Wang**, “Misconception with Pad-Based CDM ESD Protection”, **Invited**, *Proc. IEEE Electron Devices Technology and Manufacturing Conference (EDTM)*, pp. 266-269, 2020.
- Z. Pan, T. Lang, Z. Li, G. Chen and Albert Wang, “A Study of Optical Tag Detection Using Rolling Shutter Based Visible Light Communications”, *Proc. IEEE Global Communications Conference (GLOBECOM)*, 2019.
- C. Li, F. Zhang, M. Di, Z. Pan and **Albert Wang**, “Advances in 3D Heterogeneous Structures and Integration for Future ICs”, **Invited**, *Proc. IEEE SOI-3D-Subthreshold Microelectronics Technology Unified Conference (S3S)*, 2019. DOI: 978-1-7281-3523-6/19/\$31.00 ©2019 IEEE
- F. Zhang, C. Li, C. Wang, M. Di, Z. Pan, D. Harame and **Albert Wang** “A 28GHz SPDT TRx Switch with 9KV ESD Protection in 22nm SOI CMOS for 5G Mobiles”, *Proc. IEEE SOI-3D-Subthreshold Microelectronics Technology Unified Conference (S3S)*, 2019. DOI: 978-1-7281-3523-6/19/\$31.00 ©2019 IEEE (**Best Student Paper Award Finalist**)
- Z. Pan, T. Lang, C. Li, M. Di, G. Chen, R. Pai, Y. Kalay and **Albert Wang**, “Visible Light Communication Cyber-Physical Systems-on-Chip for Smart Cities”, **Keynote**, *IEEE International Conference on Information Communication and Signal Processing (ICSP)*, 2019.
- C. Li, F. Zhang, M. Di, Z. Pan and **Albert Wang**, “Developing 3D Heterogeneous Structures for Future Chips”, **Invited**, *Proc. 17th IEEE International Conference on IC Design and Technology (ICICDT)*, pp.48-51, 2019.
- M. Di, H. Wang, F. Zhang, C. Li, Z. Pan and **Albert Wang**, “Does CDM ESD Protection Really Work?”, **Invited**, *Proc. IEEE Workshop on Microelectronics and Electron Devices (WMED)*, 2019.
- T. Lang, Z. Dong, Z. Li, Z. Pan, G. Chen and Albert Wang, “LED VLC/VLP Technologies IoT Applications”, **Keynote**, *Proc. IEEE International Symposium on Communications (ISCOMM)*, 2019.

- *C. Li, Q. Chen, J. Ng, F. Zhang, H. Wang, M. Di, Y. Xie and Albert Wang*, “Graphene-Based on-Chip ESD Protection”, **Invited**, *Proc. IEEE Electron Devices Technology and Manufacturing Conference (EDTM)*, pp.176-178, 2019.
- *F. Zhang, C. Li, C. Wang, M. Di, Q. Chen, H. Wang, H. Zhao and Albert Wang*, “Cell-by-Cell SCR ESD Protection Structures in 28nm CMOS”, *Proc. IEEE Electron Devices Technology and Manufacturing Conference (EDTM)*, pp.327-329, 2019.
- *C. Li, Q. Chen, F. Zhang, J. Ng, W. Zhang, R. Ma, Albert Wang, Y-H Xie*, “Graphene NEMS Switches for on-Chip ESD Protection”, **Invited**, *ProgramBook International Symposium on Low Dimensional Materials for Optoelectronics (LDMO)*, pp. 14, 2018.
- *T. Lang, Z. Li, F. Lu, Z. Dong, L. Wang, C. Li, F. Zhang, G. Chen and Albert Wang*, “LED-Based Visible Light Communication and Positioning Technology and SoCs”, **Invited**, *Proc. IEEE International Conference on Solid-State and Integrated Circuit Technology (ICSICT)*, 2018.
- *C. Li, F. Zhang, C. Wang, Q. Chen, F. Lu, H. Wang, M. Di, Y. Cheng, H. Zhao and Albert Wang*, “Temperature Dependence of Diode and ggNMOS ESD Protection Structures in 28nm CMOS”, *Proc. IEEE International Conference on Solid-State and Integrated Circuit Technology (ICSICT)*, 2018.
- *H. Wang, F. Zhang, C. Li, M. Di and Albert Wang*, “Chip-Level CDM Circuit Modeling and Simulation for ESD Protection Design in 28nm CMOS”, *Proc. IEEE International Conference on Solid-State and Integrated Circuit Technology (ICSICT)*, 2018.
- *T. Lang, E. Torres, A. D. Reeves II, S. Cerillo-Marchan, R. Carrasco, R. Rodriguez, Albert Wang and G. Chen* “Modeling and experiment verification of non-line-of-sight ultraviolet overwater communication channel”, *Proc. SPIE 10770, Laser Communication and Propagation through the Atmosphere and Oceans VII*, 1077007, 2018, SPIE Proceedings Vol. 10770, pp. 1077007-1 to 1077007-7.
- *F. Lu, Z. Dong, L. Wang and Albert Wang*, “Visible Light Communication System-on-a-Chip”, **Invited**, *Proc. IEEE Conference on Electron Devices and Solid-State Circuits (EDSSC)*, 2018.
- *C. Wang, X. S. Wang, F. Zhang, C. Li, M. Di and Albert Wang*, “ESD and RF Switch Co-Design in SOI CMOS for Smartphones from 2G to 5G”, **Invited**, *Proc. IEEE Texas Symposium on Wireless and Microwave Circuits and Systems (WMCS)*, 2018.
- *C. Wang, F. Lu, Q. Chen, F. Zhang, C. Li, D. Wang and Albert Wang*, “A Study of Impacts of ESD Protection on 28/38GHz RF Switches in 45nm SOI CMOS for 5G Mobile Applications”, *Proc. IEEE Radio and Wireless Symposium*, pp.157-160, 2018.
- *Q. Chen, C. Wang, F. Zhang, C. Li and Albert Wang*, “3D Heterogeneous Integration Enabling Future RF ICs”, **Invited**, *Proc. IEEE Radio and Wireless Symposium*, pp.188-190, 2018.
- *C. Wang, F. Lu, Q. Chen, F. Zhang, C. Li, D. Wang and Albert Wang*, “A Study of Interferences Inside an RF Switch Array in 45nm SOI CMOS”, *Proc. IEEE SOI-3D-Subthreshold Microelectronics Technology Unified Conference (S3S)*, 2017.
- **Albert Wang**, “3D Heterogeneous Integration Enabling Next-Generation ICs”, **Keynote**, *Proc. IEEE International Conference on ASIC (ASICON)*, K2-2, 2017
- *Q. Chen, C. Li, F. Lu, C. Wang, F. Zhang, T. Wu, X. Xie, K. Zhang, X. Li, J. Ng, Y-H. Xie and Albert Wang*, “Characterization of Single-Crystalline Graphene ESD

Interconnects”, **Invited**, *IEEE International Conference on ASIC (ASICON)*, pp.977-980, 2017.

- *C. Wang, F. Zhang, F. Lu, Q. Chen, C. Li, M. Zhao, H. Gu, G. Feng, H. Wu, T. Tang, Y. Cheng and Albert Wang*, “A Comparison Study of DTSCR by TCAD and VFTLP for CDM ESD Protection”, *Proc. IEEE 11th Int'l Symp. Physical & Failure Analysis of ICs (IPFA)*, 2017.
- *F. Zhang, C. Wang, F. Lu, Q. Chen, C. Li, D. Li, S. Yu, Y. Cheng and T. Tang, Y. Cheng and Albert Wang*, “Circuit-Level ESD Protection Simulation Using Behavior Models in 28nm CMOS”, *Proc. IEEE 11th Int'l Symp. Physical & Failure Analysis of ICs (IPFA)*, 2017.
- *C. Li, C. Wang, Q. Chen, F. Zhang, F. Lu, X. Shi, Y. Yang, H. Li, G. Chen, T. Li, D. Feng, T. Tang, Y. Cheng and Albert Wang*, “Characterization and Analysis of Diode-String ESD Protection in 28nm CMOS by VFTLP”, *Proc. IEEE 11th Int'l Symp. Physical & Failure Analysis of ICs (IPFA)*, pp.1-4, 2017.
- *F. Zhang, C. Wang, F. Lu, Q. Chen, C. Li and Albert Wang*, “Full-Chip ESD Protection Design Verification Method for HV ICs with Multiple Power Domains”, *Proc. IEEE Conference on Industrial Electronics and Applications (ICIEA)*, pp. 281-284, 2017.
- *J. Ng, W. Zhang, Y-H. Xie, Q. Chen, R. Ma and Albert Wang*, “Optimization of Suspended Graphene NEMS devices for Electrostatic Discharge Applications”, *Proc. IEEE International Conference on Nano/Micro Engineered and Molecular Systems (NEMS)*, pp. 364-369, 2017.
- *Q. Chen, C. Li, F. Lu, C. Wang, F. Zhang, J. Ng, Y-H. Xie and Albert Wang*, “TLP Measurement and Analysis of Graphene NEMS Switches for on-Chip ESD Protection”, *Proc. IEEE International Conference on Nano/Micro Engineered and Molecular Systems (NEMS)*, pp.370-374, 2017.
- *Q. Chen, C. Li, J. Ng, F. Lu, C. Wang, F. Zhang, R. Ma, Y-H Xie and Albert Wang*, “Transient Characterization of Graphene NEMS Switch ESD Protection Structures”, *Proc. IEEE Electron Devices Technology and Manufacturing Conference (EDTM)*, pp.95-96.
- *Albert Wang, Q. Chen, C. Li, F. Lu, C. Wang, F. Zhang, X. S. Wang, J. Ng, Y-H. Xie, R. Ma, L. Wang and L. Lin*, “More-Than-Moore: 3D Heterogeneous Integration into CMOS Technologies”, **Invited**, *Proc. IEEE International Conference on Nano/Micro Engineered and Molecular Systems (NEMS)*, 2017.
- **Albert Wang, F. Lu, Q. Chen, C. Wang, C. Li and F. Zhang**, “Keynote: Integrated Design-for-Reliability for ICs”, **Plenary Keynote**, *Proc. 8th IEEE Latin American Symposium on Circuits and Systems (LASCAS)*, 2017.
- *C. Wang, F. Lu, R. Ma, Q. Chen, F. Zhang, C. Li, Y. Cheng, T. Tang and Albert Wang*, “A Study of Accurate Extraction of ESD Parasitic Capacitance”, **Invited**, *Proc. IEEE International Conference on Solid-State and Integrated Circuit Technology (ICSICT)*, pp. 437-440, 2016.
- *F. Lu, Z. Dong, C. Wang, Q. Chen, R. Ma, F. Zhang, C. Li and Albert Wang*, “Ultra-High Precision Bandgap Voltage Reference Using a Novel Current Trimming Technique”, **Invited**, *Proc. IEEE International Conference on Solid-State and Integrated Circuit Technology (ICSICT)*, pp. 77-80, 2016.

- **Albert Wang**, “Integrated Design-for-Reliability by 3D Heterogeneous Integration: Cross-Layer Co-Design at IC, Packaging and Board Levels”, **Plenary Keynote**, *IEEE the International Conference on Electronic Packaging Technology (ICEPT)*, 2016.
- *R. Ma, F. Lu, Q. Chen, C. Wang, F. Liu, W. Zou and Albert Wang*, “A 2.22–2.92GHz LC-VCO Demonstrated with An Integrated Magnetic-Enhanced Inductor in 180nm SOI CMOS”, *Proc. IEEE RFIC*, pp.110-113, 2016, **Best Student Paper Award Finalist**
- *Q. Chen, R. Ma, F. Lu, C. Wang, M. Liu, W. Zhang, M. Xia and Y-H. Xie, Y. Cheng and Albert Wang* “Systematic Transient Characterization of Graphene Interconnects for on-Chip ESD Protection”, *Proc. IEEE International Reliability Physics Symposium (IRPS)*, 2016.
- *T. Lang, Z. Li, Albert Wang and G. Chen*, “Hemispherical Lens Featured Beehive Structure Receiver on Vehicular Massive MIMO Visible Light Communication System”, *International Conference on Internet of Vehicles*, pp.469-477, 2015. DOI: 10.1007/978-3-319-27293-1_41
- **Albert Wang, C. Wang, L. Wang, F. Lu, R. Ma and D. Li**, “Whole-Chip ESD Design Verification by CAD: Challenges & Solutions”, **Plenary Keynote**, *Proc. IEEE International Conference on ASIC (ASICON)*, K-6, 2015.
- *W. Zhang, Q. Chen, M. Xia, R. Ma, F. Lu, C. Wang, Albert Wang and Y-H. Xie*, “TLP Evaluation of ESD Protection Capability of Graphene Micro-Ribbons for ICs”, **Invited**, *Proc. IEEE International Conference on ASIC (ASICON)*, 2015.
- *L. Wang, R. Ma, F. Lu, Z. Dong, X. Wang and Albert Wang* “Function-Based ESD Protection Circuit Design Verification for BGA Pad-Ring Array”, **Invited**, *Proc. IEEE International Conference on ASIC (ASICON)*, 2015.
- *F. Lu, Z. Dong, L. Wang, R. Ma, C. Zhang, H. Zhao and Albert Wang*, “Comprehensive ESD Co-Design with High-Speed and High-Frequency ICs in 28nm CMOS: Characterization, Behavioral Modeling, Extraction and Circuit Evaluation”, *Proc. IEEE RFIC Symposium*, pp. 409-412, 2015.
- *Z. Dong, F. Lu, R. Ma, L. Wang, C. Zhang, G. Chen, Albert Wang and B. Zhao*, “An Integrated Transmitter for LED-Based Visible Light Communication and Positioning System in A 180nm BCD Technology”, *Proc. IEEE Bipolar/BiCMOS Circuits and Technology Meeting (BCTM)*, pp. 84-87, 2014.
- *L. Wang, R. Ma, C. Zhang, Z. Dong and Albert Wang* “Behavior Modeling for Whole-Chip HV ESD Protection Circuits”, *Proc. IEEE 26th Int'l Symposium on Power Semiconductor Devices and ICs (ISPSD)*, pp. 182–184, 2014. DOI: 10.1109/ISPSD.2014.6856006
- *L. Wang, R. Ma, C. Zhang, Z. Dong, F. Lu, Albert Wang, X. Wang, J. Liu, S. Fan, H. Tang, B. Chi, L. Wu and T. L. Ren*, “Scalable Behavior Modeling for SCR Based ESD Protection Structures for Circuit Simulation”, *Proc. IEEE ISCAS*, pp.2333-2336, 2014.
- *Z. Dong, F. Lu, R. Ma, L. Wang, C. Zhang, H. Zhao, Albert Wang and B. Zhao*, “Field-Dispensable on-Chip ESD Protection for Ultra-High-Speed ICs”, **Keynote**, *Proc. IEEE ICCDCS*, pp. 12-16, 2014. ISBN 978-1-4799-4684-6.
- *Z. Dong, F. Lu, L. Wang, R. Ma, C. Zhang, H. Zhao, Albert Wang, S. Wen, R. Wong, R. Fung, C. Chu, J. Watt, A. Jahanzeb and P. Liaw*, “ESD Characterization and Design Guidelines for Interconnects in 28nm CMOS”, *Proc. IEEE International Interconnect Technology Conference/Advanced Metallization Conference (IITC)*, pp.99-101, 2014.

- *Z. Shi, X. Wang, Albert Wang* and Y. Cheng, “A 5kV ESD-Protected 2.4GHz PA in 180nm RFCMOS Optimized by ESD-PA Co-Design Technique”, *Proc. IEEE ASICON*, DOI: 10.1109/ASICON.2013.6811874, pp. 1-4, 28-31, 2013.
- *S. Fan, Albert Wang* and B. Zhao, “Folding and Interpolation ADC Design Methodology”, *Proc. IEEE ASICON*, DOI: 10.1109/ASICON.2013.6811871, pp. 1-4, 28-31, 2013.
- *H. Tang, Y. Peng, X. Lu, H. Wang and Albert Wang*, “Quantitative Analysis for High Speed Interpolated/Averaging ADC”, *Proc. IEEE ASICON*, pp. 1-4, 28-31, 2013. DOI: 10.1109/ASICON.2013.6811870
- *X. S. Wang, X. Wang, Z. Dong, F. Lu, L. Wang, R. Ma, C. Zhang, Albert Wang, C. P. Yue, D. Wang and A. Joseph*, “Concurrent Design Analysis of an 8500V ESD-Protected SP10T Switch in SOI CMOS”, **Invited (Late News)**, *Proc. IEEE SOI-3D-Subthreshold Microelectronics Technology Unified Conference (S3S)*, 2013.
- *L. Wang, R. Ma, C. Zhang, Z. Dong, X. Wang, Z. Shi, J. Liu, L. Lin, H. Zhao, F. Lu, C. Yang, J. Zhan, T. Ren, R. Huang and Albert Wang* “Heterogeneous Integration of Nano Enabling Devices for 3D ICs”, **Invited**, *Proc. IEEE Int'l Symp. Low Power Electronics and Design (ISLPED)*, pp.249-255, 2013.
- *L. Wang, X. Wang, Z. T. Shi, R. Ma, C. Zhang, Z. Dong, F. Lu, H. Zhao and Albert Wang*, “Scalable Behavior Modeling for 3D Field-Programmable ESD Protection Structures”, *Proc. IEEE CICC*, 2013.
- *X. S. Wang, X. Wang, F. Lu, L. Wang, R. Ma, Z. Dong, L. Sun, Albert Wang, C. P. Yue, D. Wang and A. Joseph*, “A Smartphone SP10T T/R Switch in 180nm SOI CMOS with 8kV ESD Protection by Co-Design”, *Proc. IEEE CICC*, 2013.
- *X. Wang, Bin Zhao, Li Wang, R. Ma, Z. Dong, C. Zhang and Albert Wang*, “Concurrent Design of Wideband RFIC and ESD”, **Invited**, *Proc. IEEE EDSSC*, 2013.
- *R. Ma, L. Wang, C. Zhang, F. Lu, Z. Dong, Albert Wang, W. Lu, Y. Song and B. Zhao*, “TLP and HBM ESD Test Correlation for Power ICs”, *Proc. IEEE EDSSC*, 2013.
- *L. Wang, C. Zhang, Z. Dong, R. Ma, X. Wang, Z. Shi, H. Zhao, J. Liu, F. Lu, Albert Wang and Y. Cheng*, “Nano Enabled 3D Integration of on-Chip ESD Protection for ICs”, **Invited**, *Proc. IEEE Conf. Nanotechnology*, pp. 19-23, 2013.
- *L. Wang, X. Wang, Z. Shi, R. Ma, J. Liu, Z. Dong, C. Zhang, F. Lu, L. Lin, H. Zhao, Albert Wang and Y. Cheng*, “Scalable Behavior Modeling for Nano Crossbar ESD Protection Structures by Verilog-A”, *Proc. IEEE Conf. Nanotechnology*, pp. 452-455, 2013.
- *X. Wang, Z. Shi, J. Liu, L. Wang, R. Ma, H. Zhao, Z. Dong, C. Zhang and Albert Wang*, “Nano Switching Crossbar Array ESD Protection Structures”, *Proc. IEEE RFIC*, pp.389-392, 2013.
- *S. Wang, F. Yao, L. Wang, R. Ma, C. Zhang, Z.Y. Dong, Albert Wang, Z. Shi, Y. Cheng, B. Chi and T. Ren*, “Design and Analysis of Full-Chip HV ESD Protection in BCD30V for Mixed-Signal ICs”, *IEEE ISCAS*, pp.1059-1062, 2013.
- *X. Yu, B. Chi, M. Wei, Albert Wang, T. Ren and Z. Wang*, “A half rate CDR with DCD cleaning up and quadrature clock calibration for 20Gbps 60GHz communication in 65nm CMOS”, *Proc. IEEE ISCAS*, pp.962-965, 2013.
- *N. Qi, Z. Song, B. Chi, Albert Wang, T. Ren and Z. Wang*, “A multi-mode complex bandpass filter with gm-assisted power optimization and I/Q calibration”, *Proc. IEEE ISCAS*, pp.1845-1848, 2013.

- *X. Yu, B. Chi, M. Wei, Albert Wang, T. Ren and Z Wang, “A half rate CDR with DCD cleaning up and quadrature clock calibration for 20Gbps 60GHz communication in 65nm CMOS”, IEEE International Symposium on Circuits and Systems (ISCAS), pp 962-965, 2013.*
- *R. Zhu, F. Yao, S. J. Wang, Albert Wang, Liji Wu, X. M. Zhang and B. Y. Chi, “A Study of Process/Device/Layout Co-Design for Full-Chip ESD Protection in BCD Technology”, Proc. IEEE International Conference on Solid-State and Integrated Circuit Technology (ICSICT), pp. 1-3, 2012. DOI: 10.1109/ICSICT.2012.6467756.*
- *R. Ma, Z. Shi, X. Wang, J. Liu, H. Zhao, L. Wang, Z. Dong, C. Zhang, L. Lin, H. Zhou, Albert Wang, J. Liu and Y. Cheng, “Design and Analysis of New Silicided Nano Crystal Dots Field Programmable ESD Protection Structures in BiCMOS”, Proc. IEEE BCTM, pp. 5-8, 2012.*
- *J. Liu, Z. T. Shi, X. Wang, H. Zhao, L. Wang, C. Zhang, Z. Dong, L. Lin, Albert Wang, Y. Cheng and B. Zhao, “Field Programmable SONOS ESD Protection Design”, Proc. IEEE Custom Integrated Circuits Conference (CICC), 2012.*
- *L. Wang, R. Ma, Albert Wang, X. Wang, B. Zhao, Shawn Wang, P. Yue, Z. Shi and Y. Cheng, “A Design Technique Overview on Broadband RF ESD Protection Circuit Designs”, Proc. IEEE MWSCAS, pp.590-593, 2012. Invited.*
- *J. Zhan, X. Wang, Q. Fang, Z. Shi, Y. Yang, T. Ren, Albert Wang, Y. Cheng, X. Li and C. Yang, “Stacked-Spiral RF Inductors with Fully-Filled Vertical Nano-Particle Magnetic Core”, Proc. IEEE RFIC Symposium, pp367-370, 2012.*
- *Z. Shi, X. Wang, J. Liu, L. Lin, H. Zhao, Q. Fang, L. Wang, C. Zhang, S. Fan, H. Tang, B. Li, Albert Wang, J. Liu, Y. Cheng and B. Zhao, “Nano Crystal Quantum Dots Tunable On-Chip ESD Protection”, Proc. IEEE Radio-Frequency IC Symposium (RFIC), pp359-362, 2012. Best Student Paper Award.*
- *X. Wang, Z. Shi, J. Liu, Q. Fang, H. Zhao, L. Wang, C. Zhang, Albert Wang, B. Zhao, L. Yang, G. Zhang and Y. Cheng, “Recent Advances in ESD Protection Design for Ultra Wideband High Data Rate ICs”, Proc. IEEE International Symposium on Circuits and Systems (ISCAS), pp2131-2134, 2012.*
- *C. Yang, J. Zhan, X. Wang, Q. Fang, Z. Shi, Y. Yang, T.-L. Ren, Albert Wang and X. Li, “On-Chip Stacked-Spiral RF Inductors with Vertical Nano-Particle-Magnetic-Medium in CMOS”, Proc. IEEE MEMS Conference, pp.721-724, 2012.*
- *J. Liu, X. Wang, H. Zhao, Q. Fang, Z. Shi, L. Wang, C. Zhang, Albert Wang and B. Zhao, “ESD Protection and Biomedical Integrated Circuit Co-Design Techniques”, Proc. IEEE Biomedical Circuits and Systems Conference (BioCAS), pp.405-408, 2011.*
- *J. Liu, L. Zhang, Z. Shi, X. Wang, L. Lin, L. Wang, C. Zhang, Albert Wang, Y. Cheng, R. Huang, B. Zhao and G. Zhang, “Characterizing Phase Switching Structures for ESD Protection”, Proc. IEEE Bipolar/BiCMOS Circuits and Technology Meeting (BCTM), pp.239-242, 2011.*
- *J. Liu, L. Zhang, X. Wang, L. Lin, Z. Shi, Albert Wang, R. Huang, G. Zhang, S.-J. Wen and R. Wong, “Nano Crossbar Electrostatic Discharge Protection Design”, Proc. IEEE Radio-Frequency IC Symposium (RFIC), 2011.*
- *J. Liu, L. Lin, X. Wang, H. Zhao, H. Tang, Q. Fang, Albert Wang, L. Yang, H. Xie, S. Fan, B. Zhao, G. Zhang and X. G. Wang, “Tunable Low-Voltage Dual-Directional ESD Protection for RFICs”, Proc. IEEE Radio and Wireless Symposium (RWS), pp.279-282, 2011.*

- *X. Wang, S. Fan, B. Qin, L. Lin, Q. Fang, H. Zhao, H. Tang, J. Liu, Z. Shi, Albert Wang*, L. Yang and Y. Cheng, “A 0.05pJ/p-mV 5th-Derivative Pulse Generator for Full-Band IR UWB Transceiver in 0.18μm CMOS”, *Proc. IEEE Radio-and Wireless Symposium (RWS)*, pp. 70-73, 2011
- *X. Wang, S. Fan, B. Qin, J. Liu, L. Lin, H. Tang, H. Zhao, Q. Fang, Albert Wang*, J. He, B. Zhao, “Full Band UWB LNA with 8kV+ ESD Protection in RFCMOS”, *Proc. IEEE Radio and Wireless Symposium (RWS)*, pp. 267-270, 2011.
- *Z. Shi, J. Liu, X. Wang, L. Lin, Albert Wang*, Y. Cheng and L. Yang, “Design and Analysis of Low-Voltage Silicon-Controlled Rectifier ESD Protection Circuit”, *Proc. IEEE International Conference on Electron Devices and Solid-State Circuits (EDSSC)*, DOI: [10.1109/EDSSC.2010.5713722](https://doi.org/10.1109/EDSSC.2010.5713722), 2010.
- *S. J. Wang, F. Yao, B. Qin, H. Y. Chen, X. Wang, H. Zhao, Q. Fang, L. Lin and Albert Wang*, “Analysis and Optimization of HV ESD Protection”, *Proc. IEEE International Conference on Electron Devices and Solid-State Circuits (EDSSC)*, DOI: [10.1109/EDSSC.2010.5714031](https://doi.org/10.1109/EDSSC.2010.5714031), 2010.
- *S. Fan, L. Lin, X. Wang, H. Tang, Q. Fang, H. Zhao, J. Liu, Albert Wang, R. Zhan, S.-J. Wen and R. Wong*, “ESDcat: New Pathway to Whole-Chip ESD Design Verification by CAD”, *Proc. Taiwan ESD & Reliability Conf.*, pp.10-17, 2010. **Keynote.**
- *H. Tang, H. Zhao, X. Wang, L. Lin, Q. Fang, J. Liu, Albert Wang, S. Fan and B .Zhao*, “Capacitive Interpolated Flash ADC Design Technique”, *IEEE Int'l SoC Design Conference*, pp. 166-169, 2010.
- *X. Wang, L. Lin, H. Tang, J. Liu, Q. Fang, H. Zhao and Albert Wang, S. Q. Fan, X. Guan and B. Zhao, Z. Shi and Y. Cheng, B. Qin and L. Yang*, “UWB SoC Co-Design with ESD Protection”, *IEEE Int'l SoC Design Conference*, pp. 13-16, 2010.
- *F. Yao, X. Wang, S. Wang, B. Qin, Albert Wang, H. Cheng, S. Fan and B Zhao*, “Mixed-Mode Simulation-Design for IEC-ESD Protection“, *Proc. IEEE ICSICT*, pp.1596-1599, 2010. **Invited.**
- *H. Tang, H. Zhao, S. Fan, X. Wang, L. Lin, Q. Fang, J. Liu, Albert Wang and B. Zhao*, “Design Technique for Interpolated Flash ADC”, *Proc. IEEE ICSICT*, pp.180-183, 2010. **Invited.**
- *J. Liu, L. Lin, X. Wang, Z. Shi, S. Fan, H. Tang, Albert Wang, Y. Cheng and B. Zhao*, “Design Optimization of Adjustable Triggering Dual-Polarity ESD Protection Structures”, *IEEE Bipolar/BiCMOS Circuits and Technology Meeting (BCTM)*, pp.149-152, 2010.
- *X. Wang, B. Qin, S. Fan, H. Tang, Q. Fang, L. Lin, J. Liu, J. He, H. Zhao, Albert Wang and B. Zhao*, “A 3.1-4.8 GHz Ultra Wideband Low Noise Amplifier with Robust Full ESD Protection in CMOS”, *Proc. IEEE Intl. Conf. Ultra Wideband (ICUWB)*, pp.197-200, 2010.
- *S. Fan, H. Zhao, H. Tang, X. Wang, L. Lin, J. Liu, Q. Fang, Albert Wang and B Zhao*, “Mixed AC/DC-Coupled Averaging Technique for ADC Nonlinearity Reduction”, *2nd IEEE Asia Symposium on Quality Electronic Design (ASQED)*, pp. 102-105, 2010.
- *H. Tang, B. Qin, X. Wang, S. Fan, Q. Fang, L. Lin, J. Liu, J. He, H. Zhao, H. Tang and Albert Wang*, “A Lower-Band UWB LNA with Integrated 7kV/15kV ESD Protection”, *2nd IEEE Asia Symposium on Quality Electronic Design (ASQED)*, pp.98-101, 2010.

- *H. Tang, C. Yang, X. Wang, S. Fan, Albert Wang* and T. Ren, “On-Chip Magnetic Inductors for RFIC Applications”, *18th International Conference on Composites/Nano Engineering (ICCE-18)*, pp. 731-732, 2010.
- *J. Liu, L. Lin, X. Wang, H. Zhao, H. Tang, Q. Fang, Albert Wang, H. Chen, H. Xie, S. Fan, B. Zhao and G. Zhang*, “Vast-Fast Low-Triggering LTdSCR ESD Protection Structure for RF ICs in CMOS”, *IEEE Radio-Frequency IC Symposium (RFIC)*, pp.233-236, 2010. (**Best Student Paper candidate**)
- **A. Wang**, “Military-Scale ESD/TVS/EMI Protection for Hi-Reliability Military Electronics”, *Proc. Components for Military and Space Electronics Conference (CMSE)*, pp.157-168, 2010.
- *N. Zhang, X. Wang, H. Tang, Albert Wang, Z. Wang and B. Chi*, “Low-Voltage and High-Speed FPGA I/O Cell Design in 90nm CMOS”, *Proc. IEEE International Conference on ASIC (ASICON)*, pp.533-536, 2009.
- *C. Yang, F. Liu, T. Ren, l. Liu, J. Zhan and Albert Wang*, “Soft-Ferrite-Film Integration for on-Chip RF Passive Elements”, to appear, *International Conference on Communication Technology and VLSI Design (CommV 09)*, 2009.
- *L. Lin, X. Wang, H. Tang, Q. Fang, H. Zhao, Albert Wang, R. Zhan, H. Xie, C. Gill, B. Zhao, Y. Zhou, G. Zhang and X. Wang*, “Whole-Chip ESD Protection Design Verification by CAD”, **Invited**, *IEEE Proc. EOS/ESD Symp*, pp.28-37, 2009.
- *X. Wang, B. Qin, H. Xie, L. Lin, H. Tang, Q. Fang, H. Zhao, S. Wang, Albert Wang, H. Chen, B. Zhao, Y. Zhou, L. Yang and G. Zhang*, “FCC-EIRP-Aware UWB Pulse Generator Design Approach”, **Invited**, *Proc. IEEE Intl. Conf. Ultra Wideband (ICUWB)*, pp.592-596, 2009.
- *F. Zhang, Z. Wang, X. Wang, H. Tang, Q. Fang, Albert Wang, W. Chen, L. Yang, B. Zhao, G. Zhang, and X. Wang*, “Design Optimization and Modeling of on-Chip RF Inductors in 0.13μm and 90nm Standard CMOS”, *Proc. IEEE MWSCAS*, pp.975-978, 2009.
- *C. Yang, T. Ren, l. Liu, J. Zhan, X. Wang, Albert Wang, Z. Wu and X. Li*, “on-Chip Soft-Ferrite-Integrated Inductors for RF IC”, *Proc. IEEE Transducers*, pp. 785-788, 2009.
- *X. Wang, H. Tang, L. Lin, Q. Fang, H. Zhao, Albert Wang, G. Zhang, X. Wang, Y. Zhou, Lee Yang and H. Chen* , “ESD Protection for RF/AMS ICs: Design and Optimization”, **Invited**, *Proc. IEEE Intl. Conf. IC Design and Technology (ICICDT)*, pp25-28, 2009.
- *B. Qin, X. Wang, H. Chen, Albert Wang, Y. Hao, L. Yang and B. Zhao*, “A Single-Chip 33pJ/pulse 5th-Derivative Gaussian Based IR-UWB Transmitter in 0.13μm CMOS”, *IEEE International Symposium on Circuits and Systems (ISCAS)*, pp.401-404, 2009.
- *B. Qin, X. Wang, H. Chen, Albert Wang and B. Zhao*, “A Programmable 1.8pJ/b Gaussian Pulse Generator for Impulse UWB Transceivers in 90nm CMOS”, *Proc. IEEE Radio and Wireless Symposium (RWS)*, pp.498-501, 2009. (**Best Student Paper candidate**)
- *C. Yang, T. L. Ren, L. -T. Liu, Y. Yuan, Albert Wang and X. Wang*, “Ferrite-integrated on-chip RF solenoid inductor,” 7th IEEE Conference on Sensors (SENSORS), Lecce, Italy, pp. 1040-1043, 2008.

- *Y. Yuan, C. Yang, T. Ren, J. Zhan, L. Liu and Albert Wang*, “Design and Simulation of on-Chip Magnetic Inductors for RF ICs,” *Proc. IEEE ICSICT, IEEE 978-1-4244-2186-2/08*, pp. 523-526, 2008.
- *B. Qin, X. Wang, H. Chen, Albert Wang* and B. Zhao, “A Tunable 2.4pJ/b 1st-Order Derivative Gaussian Pulse Generator for Impulse UWB Transceivers in 0.13μm CMOS,” *Proc. IEEE ICSICT*, pp1544-1547, 2008.
- *L. Zhang, R. Huang, Albert Wang, D. Wu, R. Wang, Y. Kuang*, “The Parasitic Effects Induced by the Contact in RRAM with MIM Structure“, *Proc. IEEE ICSICT*, pp932-935, 2008.
- *X. Guan, X. Wang, L. Lin, G. Chen, Albert Wang, H. Liu, Y. Zhou, H. Chen, L. Yang and B. Zhao*, “ESD-RFIC Co-Design Methodology”, **Invited**, *Proc. IEEE RFIC*, pp467-470, 2008.
- *X. Wang, L. Lin, X. Guan, G. Chen, Albert Wang, H. Liu, Y. Zhou, L. Yang, H. Chen and B. Zhao*, “ESD-Sensitive LNA Design”, IEEE Proc. Asia-Pacific Symposium on Electromagnetic Compatibility (AP-EMC) and *19th International Zurich Symposium on Electromagnetic Compatibility*, pp. 156-159, 2008.
- *L. Lin, J. Liu, X. Wang, Albert Wang, H. Liu and Y. Zhou*, “3D Electro-Thermal Modeling for ESD protection structures in Sub-100nm CMOS”, **Invited**, *Proc. IEEE International Nanoelectronics Conference (INEC)*, pp871-874, 2008.
- *C. Yang, F. Liu, T. Ren, L. Liu, G. Chen, X. Guan, Albert Wang and Z. Yue*, “Ferrite-Partially-Filled on-Chip RF Inductor Fabricated Using Low-Temperature Nano-Powder-Mixed-Photoresist Filling Technique for Standard CMOS”, *IEEE International Electron Device Meeting (IEDM) Tech. Digest*, pp1038-1040, 2007.
- *H. Xie, X. Wang, Albert Wang, B. Zhao, Y. Zhou, B. Qin, H. Chen and Z. Wang*, “A Varying Pulse Width 5th-Derivative Gaussian Pulse Generator for UWB Transceivers in CMOS”, *Proc. IEEE Radio and Wireless Symposium (RWS)*, pp171-174, 2008.
- *X. Wang, H. Xie, Albert Wang, B. Qin, H. Chen, S. Qiao, Y. He and Y. Zhou*, “Simulation Design of a New 3.1-10.6GHz Single-Full-Band Non-Carrier Pulse-Based Ultra Wideband System”, *Proc. IEEE ASICON*, pp834-837, 2007.
- *X. Guan, G. Chen, L. Lin, X. Wang, Albert Wang, L. Yang and B. Zhao*, “A New ESD-Aware Power Amplifier Design Method”, **Invited**, *Proc. IEEE ASICON*, pp1363-1366, 2007.
- *C. Yang, F. Liu, T. Ren, L. Liu, G. Chen, X. Guan, Albert Wang and H. Feng*, “Magnetic film inductors for RF IC”, **Invited**, *Proc. ECS Int'l Semiconductor Technology Conference (ECS-ISTC)*, pp447-462, 2007. **Best Student Paper Award**.
- *H. Xie, X. Wang, Albert Wang, B. Qin, H. Chen, B. Zhao and L. Yang*, “A Broadband CMOS Multiplier-Based Correlator for IR-UWB Transceiver SoC”, *Proc. IEEE RFIC*, pp493-496, 2007.
- *C. Yang, F. Liu, T. Ren, L. Liu, G. Chen, X. Guan, Albert Wang and Z. Yue*, “Ni-Zn Ferrite Film Coated on-Chip RF Inductor Fabricated by A Novel Powder-Mixed-Photoresist Spin-Coating Technique”, *Proc. IEEE IMS*, pp465-468, 2007.
- *H. Xie, X. Wang, Albert Wang, B. Qin, H. Chen, Y. Zhou and B. Zhao*, “A Varying Pulse Width Second Order Derivative Gaussian Pulse Generator for UWB Transceivers in CMOS”, *Proc. IEEE ISCAS*, pp2794-2797, 2007.

- *H. Xie, X. Wang, Albert Wang*, Z. Wang and C. Zhang, "A Fully-Integrated Low-Power 3.1-10.6GHz UWB LNA in 0.18 μ m CMOS", *Proc. IEEE Radio and Wireless Symposium (RWS)*, pp.197-200, 2007. (*Best Student Paper candidate*)
- *C. Yang, F. Liu, T. Ren, L. Liu and Albert Z. Wang*, "On-Chip Integrated Inductors with Ferrite Thin-Films for RFIC", *Tech. Digest, IEEE International Electron Devices Meeting (IEDM)*, pp225-228, 2006.
- *H. Xie, X. Wang, Albert Wang, B. Qin, H. Chen and B. Zhao*, "An Ultra Low-Power Low-Cost Gaussian Impulse Generator for UWB Applications", *Proc. IEEE Int'l Conference on Solid-State and Integrated Circuit Technology (ICSICT)*, pp. 1817-1820, 2006.
- *H. Xie, S. Fan, X. Wang, Albert Wang, Z. Wang and H. Chen*, "A Pulse-Based Non-Carrier 7.5GHz UWB Transceiver SoC with on-Chip ADC", **Invited**, *Proc. IEEE Int'l Conference on Solid-State and Integrated Circuit Technology (ICSICT)*, pp. 1804-1807, 2006.
- *C. Yang, F. Liu, T. Ren, L. Liu and Albert Z. Wang*, "On-Chip Integrated Inductors with Ni-Zn-Cu-Fe and Y-Bi-Fe Thin-Films for RF IC", *Proc. 34th IEEE European Solid-State Device Research Conf (ESSDERC)*, pp. 194-197, 2006.
- *H. Xie, S. Fan, X. Wang, Albert Wang, Z. Wang and H. Chen*, "A Pulse-Based Full-Band UWB Transceiver SoC in 0.18 μ m SiGe BiCMOS", *Proc. IEEE International SoC Conference*, pp.73-76, 2006.
- **Albert Wang**, "UWB Radio: Big for Wireless Applications", **Invited**, *Proc. CAS IC Design and Application Workshop*, pp. 26-30, 2006.
- *Q. Wu, S. Fan, Albert Wang, K. Takasuka and S. Takeuchi*, "An Optimized Pipelined-Subranging ADC Architecture", *Proc. IEEE International Midwest Symposium on Circuits and Systems (MWSCAS)*, ISSN: 1-458-3746, ISBN: 1-4244-0173-9, IEEE 06CH-37772, pp.2-6, 2006.
- *H. Xie, S. Fan, X. Wang and Albert Wang*, "An Ultra-Low Power Pulse-Based UWB Transceiver SoC", *Proc. IEEE International Midwest Symposium on Circuits and Systems (MWSCAS)*, ISSN: 1-458-3746, ISBN: 1-4244-0173-9, IEEE 06CH-37772, pp.669-673, 2006.
- *X. Guan, H. Feng, Albert Wang, A. Ishikawa, S. Tamura, K. Takasuka, Z. Wang and C. Zhang* "A 3V 110uW 3.1ppm/ $^{\circ}$ C Curvature-Compensated CMOS Bandgap Reference", *Proc. IEEE Int'l Symp. on Circuits and Systems (ISCAS)*, pp.2861-2864, 2006.
- *X. Guan, H. Feng, Albert Wang and L. Yang*, "A New Circuit Model for Designing Fully Integrated Class-A Power Amplifier", *Proc. 25th IEEE Int'l Conference on Microelectronics (MIEL)*, **Keynote**, pp. 409-412, 2006.
- **Albert Wang, H. Feng, R. Zhan, H. Xie, G. Chen and X. Guan**, "RF ESD Protection for VDSM Si Technology", **Invited**, *Proc. ECS 5th Int'l Semiconductor Technology Conference (ECS-ISTC)*, 2006.
- *H. Xie, L. Lin, Albert Wang and R. Zhan*, "Accurate 3D Electro-Thermal Modeling for ESD Protection Structures to Nano Scale", *Proc. International Workshop on Nano CMOS*, **Invited**, pp.68-71, 2006.

- *H. Xie and Albert Wang*, “A Fine-Tuned Low-Power LNA for Lower-Band UWB Transceiver”, *Proc. IEEE International Conference on Electron Devices and Solid-State Circuits, Invited*, pp.217-220, 2005.
- **Albert Wang, X. Guan, H. Feng, Q. Wu, R. Zhan** and L. Yang, “A 2.4 GHz Fully Integrated Class-A Power Amplifier In 0.35 μ m SiGe BiCMOS Technology”, **Invited**, *Proc. IEEE Int'l Conf. on ASIC (ASICON)*, pp.360-363, 2005.
- *H. Xie, X. Wang and Albert Wang*, “A Fully-Integrated Fine-Tuned Low-Power 3.1-10.6GHz UWB LNA in 0.18 μ m SiGe BiCMOS”, *Proc. IEEE 35th European Microwave Conference, V3*. pp. 1718—1722, 2005.
- *G. Chen, H. Feng, Albert Wang* and Y. Cheng, “Noise Analysis of ESD Structures and Impacts on a Fully-Integrated 5.5GHz LNA in 0.18 μ m SiGe BiCMOS”, *Proc. IEEE 35th European Microwave Conference*, 2005.
- **Albert Wang, H. Feng, Q. Wu, X. Guan and R. Zhan** , “A 2.45GHz Wide Tuning Range VCO Using MOS Varactor in 0.35 μ m SiGe BiCMOS Technology”, **Keynote**, *Proc. IEEE International Symp. Microwave, Antenna, Propagation and EMC Technologies for Wireless Communications (MAPE)*, pp.10-13, ISBN: 0-7803-9129-2, 2005.
- *H. Xie, R. Zhan and Albert Wang*, “3D Electro-Thermal Modeling for on-Chip ESD Protection Structures”, **Invited**, *Proc. IEEE International Conference on Mixed Design of Integrated Circuits and Systems (MIXDES)*, pp. 877-880, 2005.
- *F. Liu, C. Yang, T. L. Ren, L. T. Liu, H. G. Feng, Albert Z. Wang, H. B. Long* and J Yu, “Fully Integrated Ferrite-Based Inductors for RF ICs”, *Proc. IEEE International Conference on Solid-State Sensors, Actuators and Microsystems (TRANSDUCERS), Volume 1*, pp.895 - 898, 2005.
- **Albert Wang**, “Advanced on-Chip ESD Protection Design for Integrated Circuits”, **Invited**, *Proc. IEEE Workshop and IEEE EDS Mini-colloquium on Nanometer CMOS Technology (WIMNACT-7)*, pp.9-75, 2005.
- *H. Feng, Q. Wu, X. Guan, R. Zhan, Albert Wang* and L. W. Yang, “A 5GHz Dual-Band Sub-Harmonic Direct Down-Conversion Mixer In 0.35 μ m SiGe BiCMOS”, *Proc. IEEE International Symp. Circuits and Systems (ISCAS)*, pp.4807-4810, 2005.
- *Q. Wu and Albert Wang*, “A 12bits/200MHz Resolution/Sampling/Power-Optimized ADC In 0.25 μ m SiGe BiCMOS”, *Proc. IEEE International Symp. on Circuits and Systems (ISCAS)*, pp.6174-6177, 2005.
- *R. Zhan, H. Xie, H. Feng and Albert Wang*, “ESDZapper: A New Layout-level Verification Tool for Finding Critical Discharging Path under ESD Stress”, *Proc. IEEE Asia South Pacific Design Automation Conference (ASP-DAC)*, pp. 79-82, 2005.
- *H. Xie, R. Zhan and Albert Wang*, “3D Electro-Thermal Modeling of GGNMOS ESD Protection Structure”, *Proc. IEEE Asia-Pacific Conf. on Circuits and Systems (APC-CAS)*, pp.61-64, 2004.
- *H. Feng, H. Xie, Albert Wang, Y. Cheng and S. Lloyd*, “A Full-Monolithic LNA in 0.18 μ m SiGe: Performance Variation Due to ESD Protection”, **Invited**, *Proc. IEEE International Conference on Solid-State and Integrated Circuit Technology (ICSICT)*, 0-7803-8511-X/04, *Volume 2*, pp.1226 – 1229, 2004.

- *H. Xie, R. Zhan, Albert Wang* and R. Gafiteanu, “Real 3D Electro-Thermal Simulation and Analysis for ESD Protection Structures”, *Invited, Proc. IEEE International Caracas Conference on Devices, Circuits and Systems (ICCDCS)*, pp61-64, 2004.
- *H. Feng, Albert Wang* and L. Yang, “A New 5.5GHz LNA with Gain Control and Turn-off Control for Dual-Band WLAN Systems”, *Proc. IEEE International Conference on Solid-State and Integrated Circuit Technology (ICSICT), 0-7803-8511-X/04, Volume 2*, pp.1248 - 1251, 2004.
- *H. Xie, R. Zhan, H. Feng, G. Chen, Albert Wang* and R. Gafiteanu, “A 3D Mixed-Mode ESD Protection Circuit Simulation-Design Methodology”, *Proc. IEEE Custom Integrated Circuits Conference (CICC)*, pp243-246, 2004.
- **Albert Wang**, “Protecting RF ICs: A New Reliability Challenge”, *Keynote, Proc. IEEE Asia-Pacific Radio Science Conf.*, pp.38-41, 2004.
- *G. Chen and Albert Wang*, “Evaluating RF ESD Protection Design: An Overview”, *Invited, Proc. IEEE 11th International Symp. Physical & Failure Analysis of ICs (IPFA)*, pp205-208, 2004.
- **Albert Wang**, “A Review of RF ESD Protection Design”, *Invited Plenary, Proc. IEEE Workshop on Microelectronics and Electron Devices*, pp.20-23, 2004.
- *G. Chen, H. Feng, H. Xie, R. Zhan, Q. Wu, X. Guan, Albert Wang*, K. Takasuka, S. Tamura, Z. Wang and C. Zhang, “RF Characterization of ESD Protection Structures”, *Invited, Proc. IEEE Radio Frequency Integrated Circuits Symp. (RFIC)*, pp.379-382, 2004.
- *H. Long, Z. Feng, H. Feng, Albert Wang* and T. Ren, “L-SIMULATOR: A MAGPEEC-Based new CAD Tool for Simulating Magnetic-Enhanced IC Inductors of 3D Arbitrary Geometry”, *Proc. IEEE International Symp. Circuits and Systems (ISCAS), Volume 5*, pp. V-233/237, 2004.
- *R. Zhan, H. Feng, H. Xie and Albert Wang*, “ESDInspector: A New Layout-level ESD Protection Circuitry Design Verification Tool Using a Smart-Parametric Checking Mechanism”, *Proc. IEEE International Symp. Circuits and Systems (ISCAS), Volume 5*, pp. V217-220, 2004.
- *R. Zhan, H. Feng, Q. Wu, X. Guan, G. Chen, H. Xie and Albert Wang*, “Concept and Extraction Method of ESD-Critical Parameters for Function-Based Layout Level ESD Protection Circuit Design Verification”, *Proc. IEEE Asia South Pacific Design Automation Conference (ASP-DAC)*, pp.710-712, 2004.
- **Albert Z. Wang**, “Review on ESD Protection for RF & Microwave Devices,” **Invited**, *Proc. 11th IEEE International Symposium on Electron Devices for Microwave and Optoelectronic Applications (EDMO)*, pp.170-173, 2003.
- **Albert Z. Wang**, *H. Feng, G. Chen, R. Zhan, H. Xie, Q. Wu and X. Guan*, “Key Aspects for ESD Protection Design in ICs: Mixed-Mode Simulation And RF/Mixed-Signal ESD Protection,” **Invited**, *IEEE 25th Int'l Conf. on ASIC (ASICON)*, pp.1000-1005, 2003.
- *H. Feng, R. Zhan, Q. Wu, G. Chen, X. Guan, H. Xie and Albert Z. Wang*, “Mixed-Mode ESD Protection Circuit Simulation-Design Methodology,” *Proc. IEEE Int'l Symp. Circuits and Systems (ISCAS), VI*, pp.652-655, 2003.
- *H. Feng, R. Zhan, G. Chen, Q. Wu, X. Guan, H. Xie and Albert Wang*, “Bonding-Pad-Oriented on-Chip ESD Protection Structures for ICs,” *Proc. IEEE Int'l Symp. Circuits and Systems (ISCAS), V 4*, pp.741-744, 2003.

- *G. Chen, H. Feng and Albert Wang*, “A Systematic Study of ESD Protection Structures for RF ICs,” *Proc. IEEE Symp. RF Integrated Circuits (RFIC)*, pp.347-350, 2003.
- *H. Long, Z. Feng, H. Feng and Albert Wang*, “magPEEC: Extended PEEC Modeling for 3D Arbitrary Electro-Magnetic Devices with Application for M-Cored Inductors,” *Proc. IEEE Symp. RF Integrated Circuits (RFIC)*, pp.251-254, 2003.
- **Albert Wang**, “Recent Developments in ESD Protection for RF ICs,” **Invited**, *Proc. IEEE Asia South Pacific Design Automation Conference (ASP-DAC)*, pp.171-178, 2003.
- *R. Zhan, H. Feng, G. Chen, Q. Wu, X. K. Guan and Albert Wang*, “A New Technology-independent CAD Tool for ESD Protection Device Extraction – ESDExtractor,” *Proc. IEEE/ACM Int'l Conf. Computer Aided Design (ICCAD)*, pp.510-513, 2002.
- *R. Zhan, H. Feng, Q. Wu, G. Chen, X. Guan and Albert Wang*, “A New Algorithm for ESD Protection Device Extraction Based on Subgraph Isomorphism,” *Proc. IEEE Asia-Pacific Conference on Circuits and Systems (APC-CAS)*, pp.361-366, 2002.
- *H. Feng, R. Zhan, Q. Wu, G. Chen, X. Guan and Albert Z. Wang*, “RC-SCR: A novel low-voltage ESD Protection Circuit with New Triggering Mechanism,” *Proc. IEEE Asia-Pacific Conference on Circuits and Systems (APC-CAS)*, pp.97-100, 2002.
- *H. Feng, G. Jelodin, K. Gong, R. Zhan, Q. Wu, C. Chen and Albert Wang*, “Super Compact RFIC Inductors in 0.18 μ m CMOS with Copper Interconnects,” *Proc. IEEE International Microwave Symposium (IMS) Digest, VI*, pp. 553 –556, 2002.
- **Albert Z. Wang, H. Feng, R. Zhan, G. Chen and Q. Wu**, “ESD Protection Design for RF Integrated Circuits: New Challenges,” **Invited**, *Proc. IEEE Custom Integrated Circuits Conference (CICC)*, pp.411-418, 2002.
- *H. Feng, G. Jelodin, K. Gong, R. Zhan, Q. Wu, C. Chen and Albert Wang*, “Super Compact RFIC Inductors in 0.18 μ m CMOS with Copper Interconnects,” *Proc. IEEE Radio Frequency Integrated Circuits (RFIC) Symposium*, pp. 443 –446, 2002.
- *K. Gong, H. Feng, R. Zhan and Albert Z. Wang*, “ESD-Induced Circuit Performance Degradation in RFICs,” *IEEE Proc. European Symp. Reliability of Electron Devices Failure Physics & Analysis (ESREF)*, paper B2-1, pp.1379-1383, 2001.
- *H. G. Feng, K. Gong, R. Zhan and Albert Wang*, “A Pad-Oriented Novel Electrostatic Discharge Protection Structure for Mixed-Signal ICs,” *Proc. WSES/IEEE Conferences: 5th Circuits, Systems, Communications & Computers*, pp.3421-3425, 2001.
- *H. G. Feng, K. Gong, R. Zhan and Albert Wang*, “On-Chip ESD Protection Design for ICs,” **Invited Plenary**, *Proc. WSES/IEEE 5th CSCC*, pp.4151-4164, 2001.
- *H. G. Feng, K. Gong, R. Zhan and Albert Wang*, “A Novel all-Direction on-Chip Protection Circuit,” *Proc. IEEE/IEICE Int'l Symp. Signals, Systems, and Electronics (ISSSE)*, pp.118-121, 2001.
- *H. G. Feng, K. Gong and Albert Wang*, “An ESD Protection Circuit for Mixed-Signal ICs,” *Proc. IEEE CICC*, pp.493-496, May 2001.
- **Albert Wang**, “A New Design for Complete on-Chip ESD Protection,” Technical report, ERIF, *Research News*, IIT, 2000.
- *H. G. Feng, K. Gong and Albert Wang*, “ESD Protection in Cu vs. Al: More Robustness & Less Parasitics”, *Semicon West*, San Francisco, 2000.

- **Albert Wang**, *H. Feng and K. Gong*, “On-Chip Electrostatic Discharge Protection Design in Copper Interconnects: Better ESD Performance with Less Parasitic Effects”, *IEEE 43rd Midwest Symp. Circuits and Systems*, 2000.
- *H. G. Feng, K. Gong and Albert Wang*, “A New Integrated Metal-Semiconductor Simulation Methodology for on-Chip Electrostatic Discharge Protection Design Optimization“, *Proc. IEEE/IFIP World Computer Congress Int'l Conference on Design Automation*, pp.81–85, 2000.
- *H. G. Feng, K. Gong and Albert Wang*, “ESD Protection Design Using Copper Interconnects: More Robustness and Less Parasitics,” *SRC Publication: 2000 Publications in Copper Design Challenge, Pub. P000375*, March 2000.
- *H. G. Feng, K. Gong and Albert Wang*, “A Comparison Study of ESD Protection for RFIC’s: Performance vs. Parasitics,” *Proc. IEEE RFIC Symp.*, pp.235-238, 2000.
- *K. Gong, H. G. Feng and Albert Wang*, “On Impacts of ESD Protection Structure on Circuit Performance in Aluminum and Copper Interconnects,” *Proc. IEEE 1st EIT*, paper 106-3, Chicago, June 2000.
- *H. G. Feng, K. Gong and Albert Wang*, “A Comparison Study of ESD Protection for RFIC’s: Performance vs. Parasitics,” *IEEE MTT-S Int'l Microwave Symp. (IMS) Digest*, pp.143-146, 2000.
- A. Z. Wang, “A New Design for Complete on-Chip ESD Protection,” *Proc. IEEE Custom Integrated Circuits Conference (CICC)*, pp. 87-90, May 2000.
- **Albert Z. Wang** and C. H. Tsay, “A Compact Square-Cell ESD Structure for BiCMOS ICs,” *Proc. IEEE BCTM*, pp. 46-49, May 1999.
- **Albert Wang**, C. Tsay and Q. Shan, “A Novel Dual-Direction IC ESD Protection Device,” *Proc. IEEE 7th Int'l Symp. Physical and Failure Analysis of Integrated Circuits (IPFA)*, pp.151-155, 1999.
- **Albert Wang**, C. Tsay, J. Bielawski and L. DeClue, “Design Optimization of a Practical ESD Protection Circuit by CAD: A Case Study,” *Proc. IEEE 13th UGIM*, pp. 116-119, 1999.
- **Albert Wang** and C. Tsay, “A Low-Triggering Circuitry for Dual-Direction ESD Protection,” *Proc. IEEE Custom Integrated Circuits Conference (CICC)*, pp 139-142, May 1999.
- **Albert Wang** and C. Tsay, “A Drop-in PtSi Schottky Module for BiCMOS by TCAD,” *Proc. AURORA Conf.*, San Jose, CA, February 1999.
- **Albert Wang** and C. Tsay, “A Novel Design Methodology Using Simulation for on-chip ESD Protection for Integrated Circuits,” *Proc. IEEE Intl. Conf. Solid-State & IC Technology (ICSICT)*, pp.509-512, 1998.
- **Albert Wang**, C. Tsay, A. Lele and P. Deane, “A Study of NMOS Behaviors under ESD Stress: Simulation and Characterization,” *Proc. IEEE 9th European Symp. Reliability of Electron Devices Failure Physics & Analysis*, pp.151-155, 1998.
- **Albert Z. Wang**, W. A. Anderson, B. J. Wu, M. Haase, and T. J. Mountziaris, “Zn_{0.07}Sse_{0.93} Metal-Semiconductor Field Effect Transistor,” *Proc. IEEE Cornell Conf. on Advanced Concepts in High Speed Semiconductor Devices and Circuits*, 1995.
- **Albert Z. Wang** and W. A. Anderson, “Metal-Semiconductor Contacts to n-Zn_{0.07}Sse_{0.93},” *Proc. TMS Electronic Material Conference and IEEE Device Research Conference (DRC)*, 1995.

- **Albert Z. Wang** and W. A. Anderson, *Proc. Material Research Society Spring Meeting*, 1995.
- X. Chen and **(Albert) Z. H. Wang**, “A asymmetric lightly-doped drain MOS field effect transistor,” *Proc., IEEE Intl. Conf. Solid-State & IC Technology (ICSICT)*, 1990.

U. S. PATENTS:

- **Albert Wang**, *US Patent No. 10,244,590 B2*, 2019.
- **Albert Wang**, *US Patent No. 9,741,655 B2*, 2017.
- **Albert Wang**, *US Patent No. 9,819,176 B2*, 2017.
- **Albert Wang**, *US Patent No. 9,246,328 B2*, 2016.
- **Albert Wang**, *US Patent No. 9,331,661 B2*, 2016.
- **Albert Wang**, *US Patent No. 8,879,223 B2*, 2014.
- **Albert Wang**, *US Patent No. 8,879,230 B2*, 2014.
- **Albert Wang**, *US Patent No. 8,305,722 B2*, 2012.
- **Albert Wang**, *US Patent No. 7,936,020 B1*, 2011.
- **Albert Wang**, *US Patent No. 7,327,541*, 2008
- **Albert Wang**, *US Patent No. 7,262,680*, 2007.
- **Albert Wang**, *US Patent No. 7,243,317B2*, 2007.
- **Albert Wang**, *US Patent No. 6,635,931*, 2003.
- **Albert Wang**, *US Patent No. 6,512,662*, 2003.
- **Albert Wang**, *US Patent No. 6,365,924*, 2002
- **Albert Wang**, *US Patent No. 6,258,634*, 2001.